

CHEMLINQ™ MCL-T33

Melamine Cleaning Compound - Pellets



- Strong cleaning performance
- Compatible with wide range of mold cavity designs
- Extends mold lifespan and reduces downtime

CHEMLINQ™ MCL-T33 mold cleaning compound (pellet) is composed of melamine resin, silica filler, and other additives. It is specifically formulated to remove epoxy molding compound residues and stains from metal mold dies. **CHEMLINQ™ MCL-T33** has high cohesive strength and optimized rheological properties. It effectively restores mold surface integrity, prolongs tooling lifespan, and significantly reduces mold cleaning cycle times, minimizing production downtime. Overall, this transfer-grade product is well-suited for cleaning mold dies in semiconductor packaging, where clean surfaces are essential for consistent quality and yield.

CHEMLINQ™ MCL-T33 can be used alone or in combination with CHEMLINQ™ RCS rubber cleaning sheet series to enhance cleaning performance.

Specifications

Property	Value	Unit
Appearance	White, cylindrical pellets	–
Specific Gravity	1.3–1.5	–
Density	1.2–1.5	g/cm ³
Spiral Flow	50–127	cm
Diameter Small pellets Big pellets	11, 13, 14, 16, 18, 20 40, 48, 50	mm
Weight Mini pellets Big pellets	2.8–18 30–100	g

Recommended Curing Parameters

Parameter	Value	Unit
Curing Temperature	160–190	°C
Curing Temperature	300–500	s
Mold Clamp Pressure	20–150	ton

Europe

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Instructions for Use

1. Make sure the mold temperature is ready for cleaning. Preheat it to its standard operating temperature. Remove all large contaminants prior to cleaning.
2. Place the **MCL-T33** pellets into the mold cavity. The number of pellets depends on the size of the mold and the level of contamination.
3. Close the mold and initiate a standard transfer molding cycle. This includes applying the necessary pressure and heat to activate the cleaning compound. Heat and pressure help the **MCL-T33** pellets to flow across the mold surfaces, effectively loosening and removing organic and inorganic residues.
4. After the cycle is complete, open the mold and eject the cleaning compound residue. Inspect the mold for any remaining contaminants. If necessary, repeat the process using additional pellets or in combination with other cleaning methods, such as **CHEMLINQ™ RCS** rubber cleaning sheets.
5. Perform a final inspection to ensure all residues are removed.

Storage and Handling

CHEMLINQ™ MCL-T33 is packaged in PE bags. Store the product in a cool, dry place, away from heat sources and moisture. High humidity and excessive heat can cause curing failures in the cleaning compound. The shelf life is 12 months below 25 °C. If taken from a cold room or refrigerator, thaw it in the sealed package for 18 to 24 hours until it reaches room temperature.

Use the product in a well-ventilated area. Always follow safety guidelines and wear protective equipment when handling. For more safety information, check the Material Safety Data Sheet (MSDS).

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